Abstracts

A Multilayer Bandpass Filter Integrated Into RF Module Board

H.-C. Chang, C.-C. Yeh, W.-C. Ku and K.-C. Tao. "A Multilayer Bandpass Filter Integrated Into RF Module Board." 1996 MTT-S International Microwave Symposium Digest 96.2 (1996 Vol. II [MWSYM]): 619-622.

A bandpass filter using multilayer structure is designed and manufactured. This filter is for the DECT handset RF module, hence must be compact, easy for mass-production, and low cost. This design uses standard (yet lowloss) FR4 board (epsilon r=4.8) and tapped I/O for the ease of manufacturing. A zero is introduced at the image frequency. Its multilayer structure occupies only three layers, and allows the filter to be integrated into the RF module board, while its tapped I/O increases manufacturing tolerance, and is easy for connection.

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